

Detailed description: This technical drawing shows a cross-section of a four-layer printed circuit board. The layers are labeled from top to bottom as follows: Layer 1 (Solder Level, Copper Plate, Copper Foil); Core (230um, SEE NOTE 3A); Layer 2 (Copper Foil 17um, Prepregs 120um, SEE NOTE 2A); Layer 3 (Copper Foil 17um); Core (230 um, SEE NOTE 3A); and Layer 4 (Copper Foil, Copper Plate, Solder Level). The thickness of each copper foil layer is specified as 17um, while the prepreg layer is 120um. The total thickness of the core layers is 230um. The solder levels at the top and bottom are 35um thick. Vertical arrows on the left indicate the position of each layer relative to the others.

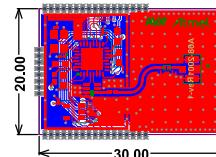
NOTE

- 1A: SURFACE PROTECTION: Chemical Gold
 - 2A: DIELECTRIC FR4 (S1000B)
 - 3A: DIELECTRIC FR4 (S1000)
 - 4A: TOTAL THICKNESS TO BE DEFINED BY MANUFACTURER
WITH RESPECT TO STANDARD FINISHING

THE BOARD MUST BE RoHS COMPLIANT

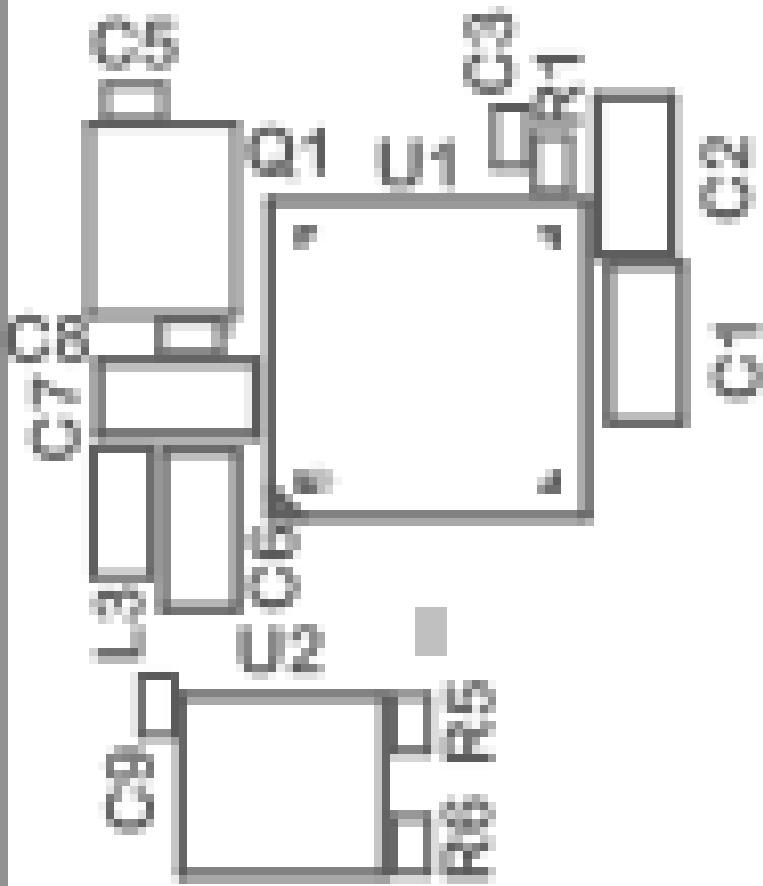
DETAIL A (CROSS-SECTION)

SCALE = NOM



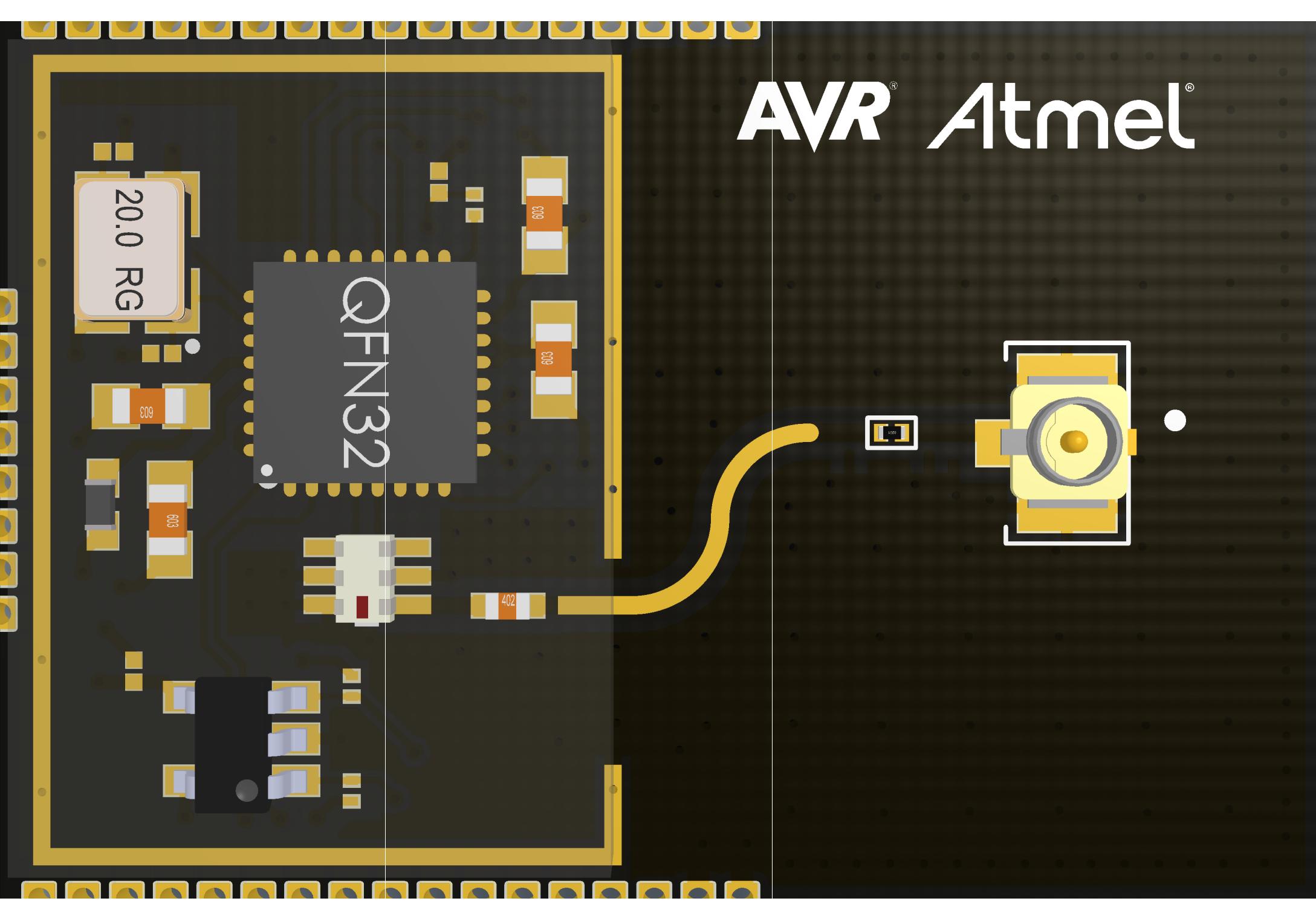
	ENGINEER:	TITLE	
	PCB DESIGNER:		
ATELIER NORWAY Vestre Rosten 79 N-7075 Trondheim	DATE: 10-02-2014	PART NO: A08-2001_Rev1.PcbDoc	REV: SCALE:
	FILE NAME: A08-2001_Rev1.PcbDoc	DWG NO:	

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